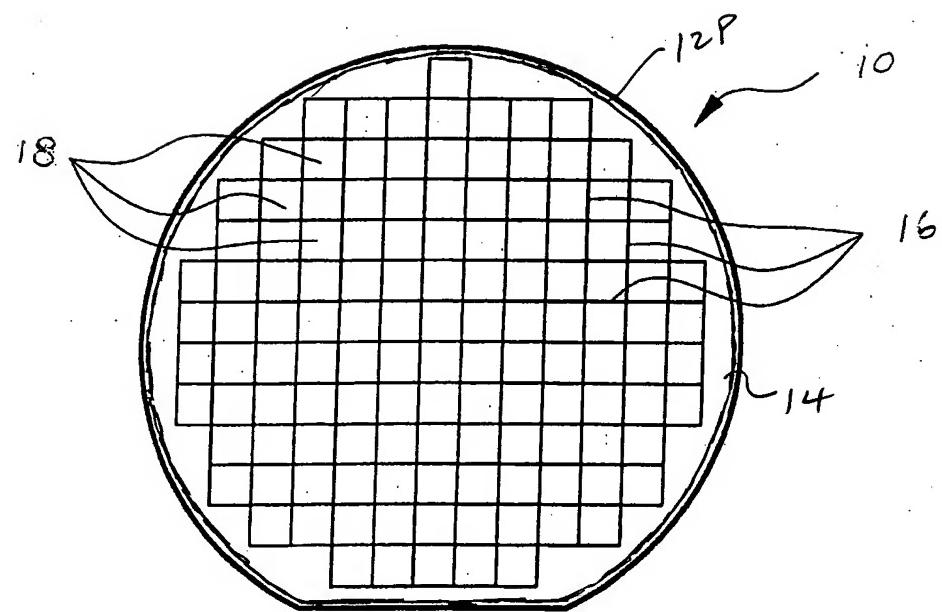


TITLE: METHOD AND APPARATUS FOR SUPPORTING WAFERS
FOR DIE SINGULATION AND SUBSEQUENT HANDLING

Inventor: Farnworth et al.
Serial No.: Not Yet Assigned
Docket No.: 2269-5529US

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FIG. 1



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Inventor: Farnsworth et al.

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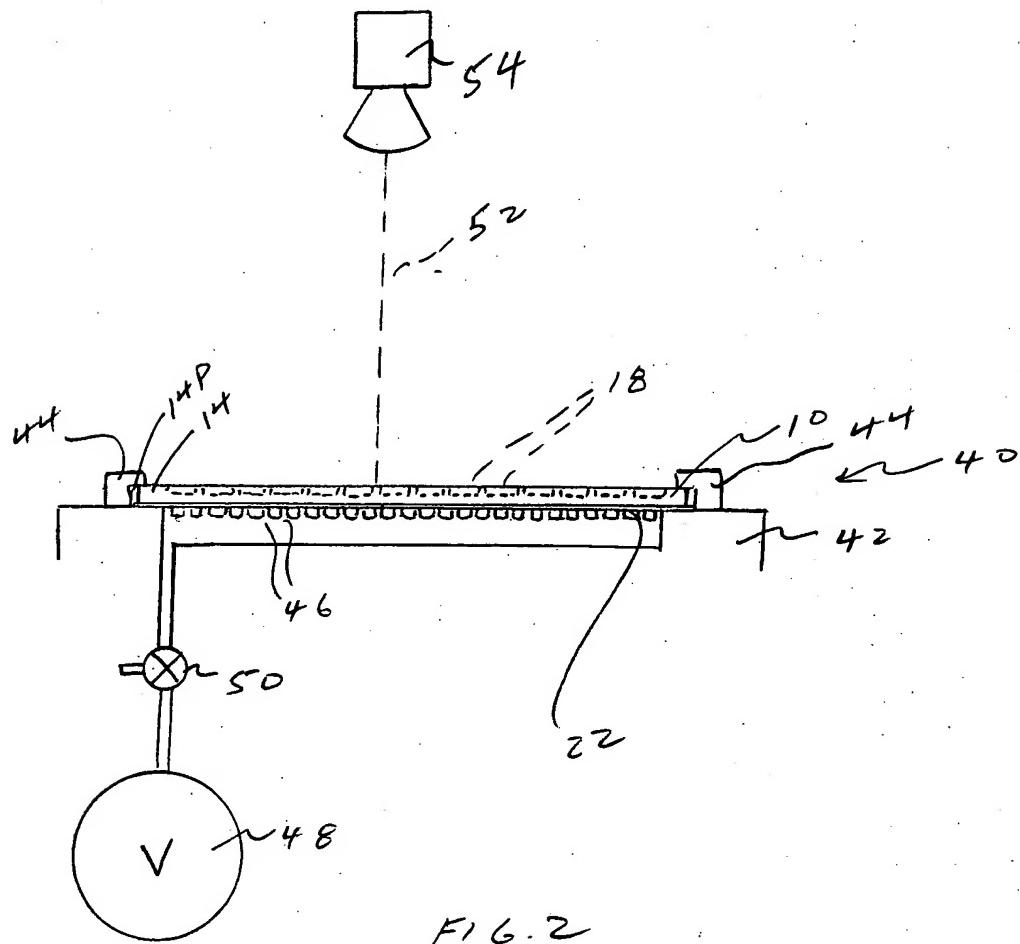


FIG. 2

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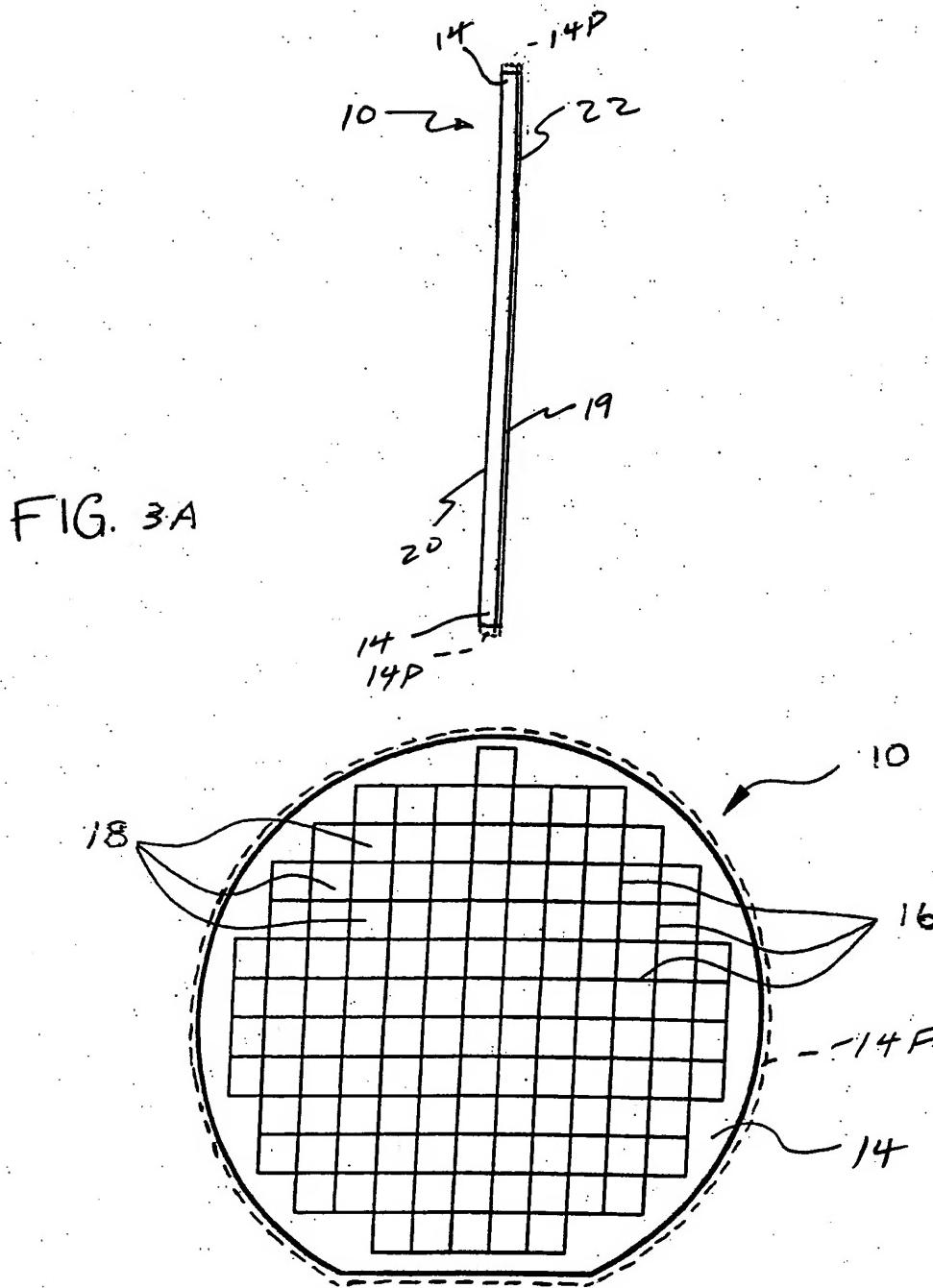


FIG. 3B

TITLE: METHOD AND APPARATUS FOR SUPPORTING WAFERS
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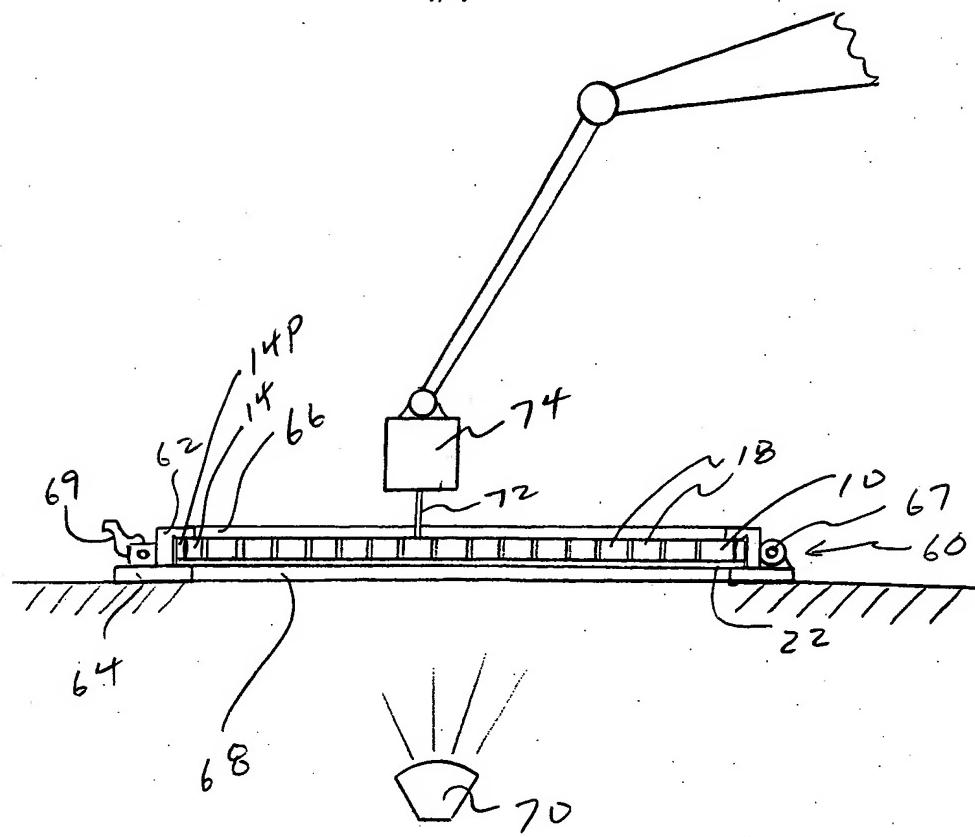


FIG. 4